Chip Module Production

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**Market-leading, innovative systems at affordable prices**

The smart card market is characterised by strong competition and falling prices for components. This requires a higher level of automation and increased efficiency, without compromising quality and precision. Face these mounting challenges head-on with **innovative machines and systems designed by ruhlamat** to perform in the most demanding production environments.

Our **affordable and industry-proven machine solutions** provide the **speed, quality and economy** that will help you to sustain and maximise profitability in the future. We offer sophisticated, **high-quality machines for the chip module production**, ranging from encapsulation, testing and encoding of IC modules to glue tape lamination of module tapes.

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**PowerSeal - Chip Module Encapsulation Machine [1]**

*Encapsulation* is the method for protecting the chip and wires against mechanical stress and environmental influences. For this purpose, cast resin is dispensed and then cured by UV light or heat, depending on the type of resin.

The **PowerSeal** offers highest quality and maximum speed for the **encapsulation of chip modules** with up to 40,000 modules/hour.

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**PowerTest - Chip Module Test System [2]**

The **inspection of IC modules** for smart cards and RFID devices, based on parametric and functional testing, is an integral part in the production flow and quality assurance.

The **PowerTest** is designed for **high-speed testing and encoding of chip modules** on 35 mm tapes. The system is also
perfectly suited for **initialisation and personalisation of IC modules**, including OS loading.

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**GTL700 - Glue Tape Lamination System** [3]

The **GTL700** is a highly reliable and **flexible system for glue tape lamination of chip module tapes** in preparation for the **hot melt implanting process**.

The very efficient system can operate stand-alone or inline, and is suitable for a wide range of IC module tapes (contact, contactless, and dual interface).

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**Links**

